

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																				
NATURE OF CONVEYANCE:	ASSIGNMENT																				
CONVEYING PARTY DATA																					
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CORRESPONDENCE DATA																					
<p>Fax Number: (214)200-0853</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000</p> <p>Email: eppsl@haynesboone.com</p> <p>Correspondent Name: HAYNES AND BOONE, LLP IP Section</p> <p>Address Line 1: 2323 Victory Avenue</p>																					

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ATTORNEY DOCKET NUMBER: 24061.1422

NAME OF SUBMITTER: David M. O'Dell

Total Attachments: 4
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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|--|
| (1) | Martin Liu | of | 3F, No. 7, Bao-an Road
Yonghe City, Taipei County 234, Taiwan, R.O.C. |
| (2) | Richard Chu | of | <u>4F, NO. 9-2, Ln. 110, Qiangang st., Shilin</u>
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| (3) | Hung-Hua Lin | of | 1F, No. 22, Alley 3, Lane 128, Jinghua Street
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Taipei City 116, Taiwan, R.O.C. |
| (4) | H. T. Huang | of | No. 4, Xiwei Neighborhood 2, Bailu Vil
Bade City, Taoyuan County 33455, Taiwan, R.O.C. |
| (5) | Jung-Huei Peng | of | 7F-1, No. 6, Zihciang 6th Street
Jhubei City, Hsinchu Hsien, Taiwan, R.O.C. |
| (6) | Yuan-Chih Hsieh | of | 4F, No. 12, Lane 1007, Daxue Road
Hsin-Chu City 300, Taiwan, R.O.C. |
| (7) | Lan-Lin Chao | of | 3F, No. 113, Zihli Street
Sindian City, Taipei County, Taiwan, R.O.C. |
| (8) | Chun-Wen Cheng | of | No. 15, Alley 11, Lane 100, Jiafeng 1st Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C. |
| (9) | Chia-Shiung Tsai | of | No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road
Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

WAFER LEVEL PACKAGING BOND

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 x filed on March 23, 2010, and assigned application no. 12/729,911 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

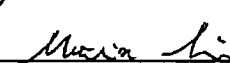
AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Martin Liu

Residence Address: 3F, No. 7, Bao-an Road
Yonghe City, Taipei County 234, Taiwan, R.O.C.

Dated: ✓ 2010. 3. 11.

✓ 
Inventor Signature

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Dated: 2010 03 11 Richard Chu
Inventor Signature

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Inventor Name: Jung-Huei Peng
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Inventor Signature

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Dated: Mar. 16, 2010

Yuan-Chih Hsieh
Inventor Signature

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Dated: Mar 11, 2010

Lan-Lin Chao
Inventor Signature

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Dated: Mar. 16, 2010

Chun-Wen Cheng
Inventor Signature

Inventor Name: Chia-Shiung Tsai

Residence Address: No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road
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Dated: 3, 16, 2010

Chia Shiung Tsai
Inventor Signature